

HM37-1609R32LF summary material content, BI Technologies Corporation

Index	Item	Material Name	Element Composition	CAS No	Material Mass (g)	Composition (g)
1	SI CORE	M21	Fe ₂ O ₃	1317-60-8	1.7020	1.0212
			MnO	1344-43-0		0.4255
			ZnO	1314-13-2		0.2553
	SU CORE	M21	Fe ₂ O ₃	1317-60-8	2.3200	1.3920
			MnO	1344-43-0		0.5800
			ZnO	1314-13-2		0.3480
2	COIL	Enamelled Copper Magnet Wire	Copper (Cu)	7440-50-8	0.2600	0.2080
			Polyester Imide (PEI)	-		0.0312
			Polyamide Imide (PAI)	-		0.0208
3	SOLDER	Lead Free Solder	Sn 96.5	7440-31-5	0.0100	0.0097
			Ag 3.0	7440-21-3		0.0003
			Cu 0.5	7440-50-8		0.0001
4	ADHESIVE	Epoxy TB2272	Bisphenol F Epoxy Resin	9003-36-5	0.0100	0.0051
			Latent Hardener	-		0.0005
			Hardener	461-58-5		0.0003
			Modified Epoxy Resin	-		0.0023
			Sb ₂ O ₃	1309-64-4		0.0005
			CaCO ₃	471-34-1		0.0010
			Others	-		0.0004
5	SPACER	Nomex Paper	Nylon66	32131-17-2	0.0050	0.0049
			Non-regulated Lubricant & Stabilizer	-		0.0001

Total Weight	4.3070
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